

REMARKS

Claims 56-99 are pending in the application with claims 56, 60, 64, 69, 74, 80, 86 and 93 being independent. Claims 56, 60, 64, 69, 74, 78-80, 84-86, 91-93, 98 and 99 have been amended. In particular, claims 56, 60, 64 and 69 have been amended to recite that the insulating layer covers at least a channel forming region of a semiconductor element of the semiconductor device, as illustrated in Figs. 5B-7 and discussed in the accompanying text. Claims 74, 78-80, 84-86, 91-93, 98 and 99 have been amended merely to replace "DLC" with the term "diamond-like carbon." As is recited in the application at page 7, lines 11-12, "DLC" is an abbreviation for "diamond-like carbon." No new matter has been added.

Claims 56-99 have been rejected as being unpatentable over the background of the invention in view of Majima.

As amended, independent claim 56 recites a method of manufacturing a semiconductor device that includes, among other steps, planarizing surfaces of electrodes and a surface of an insulating layer so that they become flush with each other, thereby filling boundary portions between the electrodes with the insulating layer. Claim 56 further recites that the insulating layer covers at least a channel forming region of a semiconductor element of the semiconductor device.

Applicant requests reconsideration and withdrawal of the rejection of claim 56 and its dependent claims because neither the background of the invention, Majima, nor any combination of the two describes or suggests having the planarized insulating layer cover at least a channel forming region of a semiconductor element of the semiconductor device, as recited in claim 56. The Examiner concedes that the background of the invention does not describe planarizing the insulating layer, and relies on Majima as describing such planarization. With reference to Figs. 2E and 2F, Majima describes planarizing a resin film 5d and pixel electrodes 4 such that a portion of the resin film 5d is left to fill a gap 5a between adjacent pixel electrodes. However, since the gap 5a does not cover the channel forming region of the semiconductor element in Majima, Majima does not describe or suggest the subject matter of claim 56 and, accordingly, the rejection of claim 56 and its dependent claims should be withdrawn.

Like claim 56, independent claims 60, 64 and 69 recite that the insulating layer covers at least a channel forming region of a semiconductor element of the semiconductor device. Accordingly, the rejection of claims 60, 64 and 69, and their dependent claims, should be withdrawn.

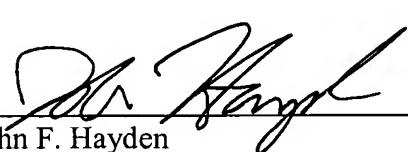
Each of independent claims 74, 80, 86 and 93 recites a method of manufacturing a semiconductor device that includes forming a diamond-like carbon film to cover electrodes. Applicant requests reconsideration and withdrawal of the rejection of claims 74, 80, 86 and 93, and their dependent claims, because neither the background of the invention, Majima, nor any combination of the two describes or suggests forming a diamond-like carbon film. While the Examiner indicates that Majima describes such film formation, applicant has been unable to find any reference in Majima to "diamond-like carbon." Nor has applicant found any reference to "DLC," "diamond-like," "diamond," or "carbon."

Applicant submits that all claims are in condition for allowance.

Enclosed is a \$110 check for the Petition for Extension of Time fee. Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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